L Numb r	Hits	Search T xt	DB	Time stamp
500	5115	(sta k or stacking or stacked) and	USPAT;	2004/06/17
500	3113	((sub trat rint rp ser rtap) n ar5	US-P PUB;	09:53
		(thr ughh le or through-h l r h l or via	EPO; JPO;	09.55
		or opening)) and le tr d and (wire or	DERWENT;	
		wiring)	IBM_TDB	
501	1164	(stack or stacking or stacked) and	USPAT;	2004/06/17
301	1104	((substrate or interposer or tape) near5	US-PGPUB;	09:53
500		(throughhole or through-hole or hole or via	EPO; JPO;	03.33
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
			IBM_IDB	
	000	or lower or second) near5 (chip or ic))	HEDAT.	2004/06/17
502	990	(stack or stacking or stacked) and	USPAT;	09:54
		((substrate or interposer or tape) near5	US-PGPUB;	09:54
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
		or lower or second) near5 (chip or ic)) and		
	057	(mount or mounted or mounting)	LIGDAT	0004/00/47
503	657	(stack or stacking or stacked) and	USPAT;	2004/06/17
		((substrate or interposer or tape) near5	US-PGPUB;	09:54
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
		or lower or second) near5 (chip or ic)) and		
		(mount or mounted or mounting) and		
		adhesive		
504	395	(stack or stacking or stacked) and	USPAT;	2004/06/17
		((substrate or interposer or tape) near5	US-PGPUB;	09:55
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
		or lower or second) near5 (chip or ic)) and		
		(mount or mounted or mounting) and		
		adhesive and ((insulating or dielectric or		•
		nonconductive or non-conductive or		
		nonconducting or non-conducting) near5		
		(substrate or interposer or tape))		
505	84	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and electrode and	DERWENT;	
		(wire or wiring) and ((first or upper or top or	IBM_TDB	
		bottom or lower or second) near5 (chip or		
		ic)) and (mount or mounted or mounting)		
		and adhesive and ((insulating or dielectric		
		orn n nductiv rnon-conductive r		
		non onducting or non-conducting) near5		
		(ubstrate rinterp ser rtape))		<u> </u>

			T	
506	41	(sta k r stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate rint rpo r rtap) near5	US-P PUB;	09:56
		(thr ughh I orthrough-h le rh le orvia	EPO; JPO;	
		r pening)).ti,ab,clm. and el trod and	DERWENT;	
		(wire rwiring) and ((first rupper or top or	IBM_TDB	
		bott m r lower or s nd) near5 (chip or	.5	
	j l			,
	Ì	ic)) and (mount or mounted or mounting)		
	İ	and adhesive and ((insulating or dielectric		
		or nonconductive or non-conductive or		
		nonconducting or non-conducting) near5		
		(substrate or interposer or tape)).ti,ab,clm.		
507	19	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
007		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
			1	09:50
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and	DERWENT;	
		electrode.ti,ab,clm. and (wire or wiring) and	IBM_TDB	
		((first or upper or top or bottom or lower or		
		second) near5 (chip or ic)) and (mount or		
		mounted or mounting) and adhesive and		
		((insulating or dielectric or nonconductive		
		or non-conductive or nonconducting or		
		non-conducting) near5 (substrate or		
		interposer or tape)).ti,ab,clm.		
508	18	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and	DERWENT;	1
		electrode.ti,ab,clm. and (wire or	IBM_TDB	
		wiring).ti,ab,clm. and ((first or upper or top		
•		or bottom or lower or second) near5 (chip		
		or ic)) and (mount or mounted or mounting)		
		and adhesive and ((insulating or dielectric		
		or nonconductive or non-conductive or		
		nonconducting or non-conducting) near5		
-		(substrate or interposer or tape)).ti,ab,clm.		
509	9	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
	i	(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and	DERWENT;	
		electrode.ti,ab,clm. and (wire or	IBM_TDB	İ
		wiring).ti,ab,clm. and ((first or upper or top		
		or bottom or lower or second) near5 (chip		
		or ic)).ti,ab,clm. and (mount or mounted or		
		mounting) and adhesive and ((insulating or		
		dielectric or nonconductive or		
		non-conductive or nonconducting or		
		non-conducting) near5 (substrate or		
		int rposer r tap)).ti,ab,clm.		
L		int iposer i tap //.ti,au,cim.	l	